

ABSTRACT OF THE DISCLOSURE

A method and a device for placing a multitude of shaped parts of solder material (20) on a bond pad arrangement (29) of a substrate (23), the bond pad arrangement including a multitude of bond pads (28), and for subsequent re-melting of the shaped parts of solder material on the bond pads (28), with arrangement of a template device (21) including a multitude of template apertures (27) for accommodating shaped parts of solder material (20) opposite a substrate (23) includes a bond pad arrangement (29), such that the shaped parts of solder material are associated with the individual bond pads (28); and application of laser energy to the shaped parts of solder material (20) accommodated in the template apertures (27) using a laser device (39) arranged at the rear of the template device (21) such that the laser energy is applied to the shaped parts of solder material through the template device.